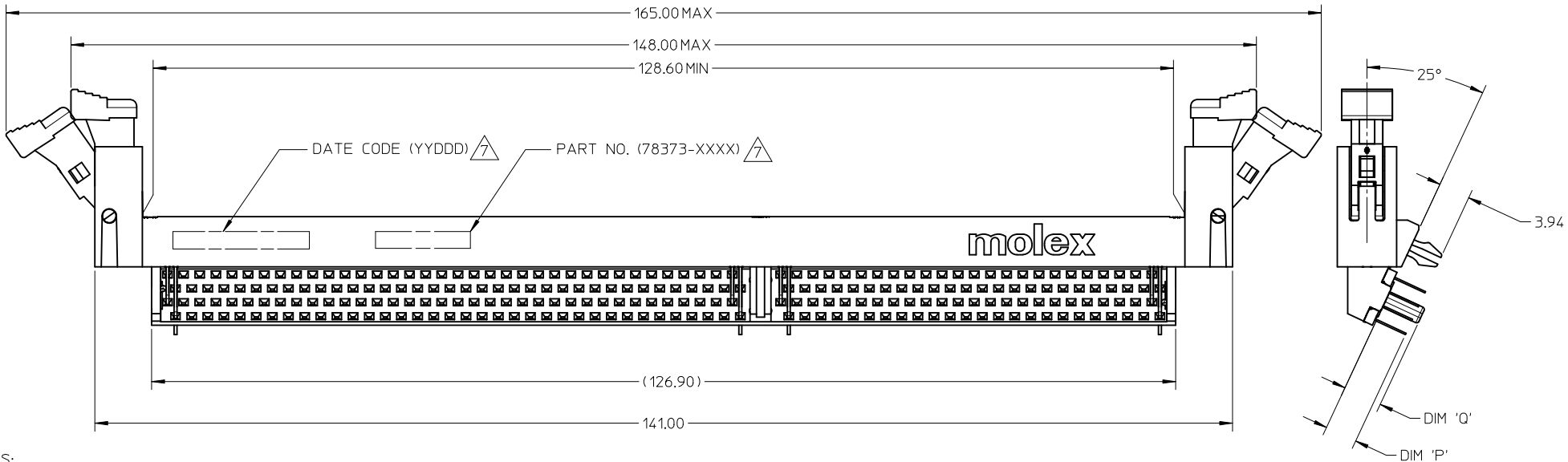
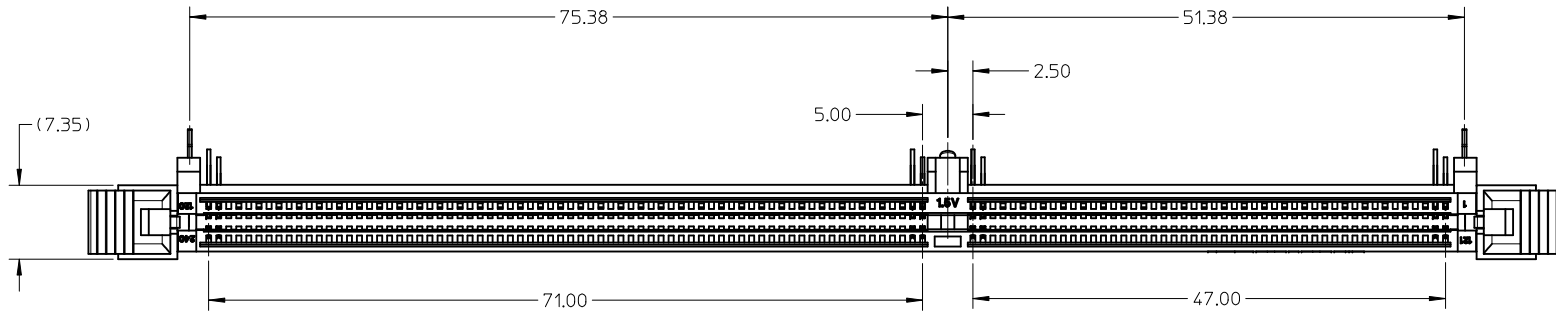


10 9 8 7 6 5 4 3 2 1



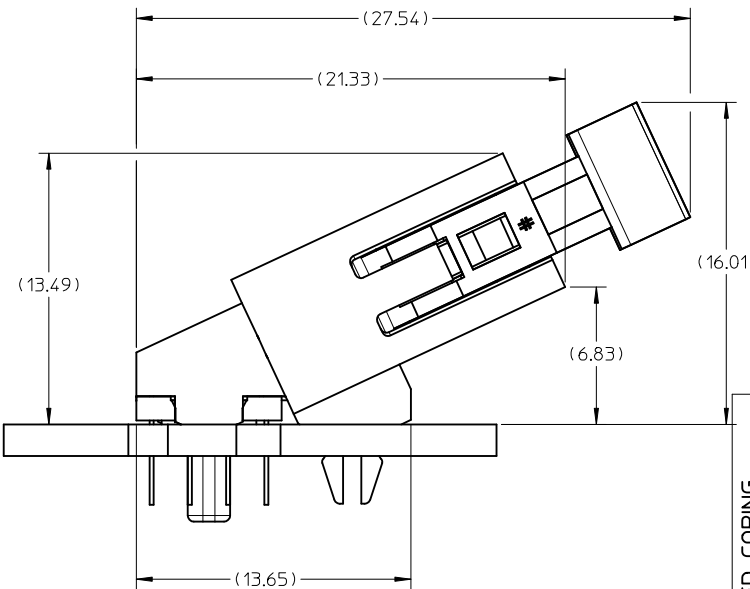
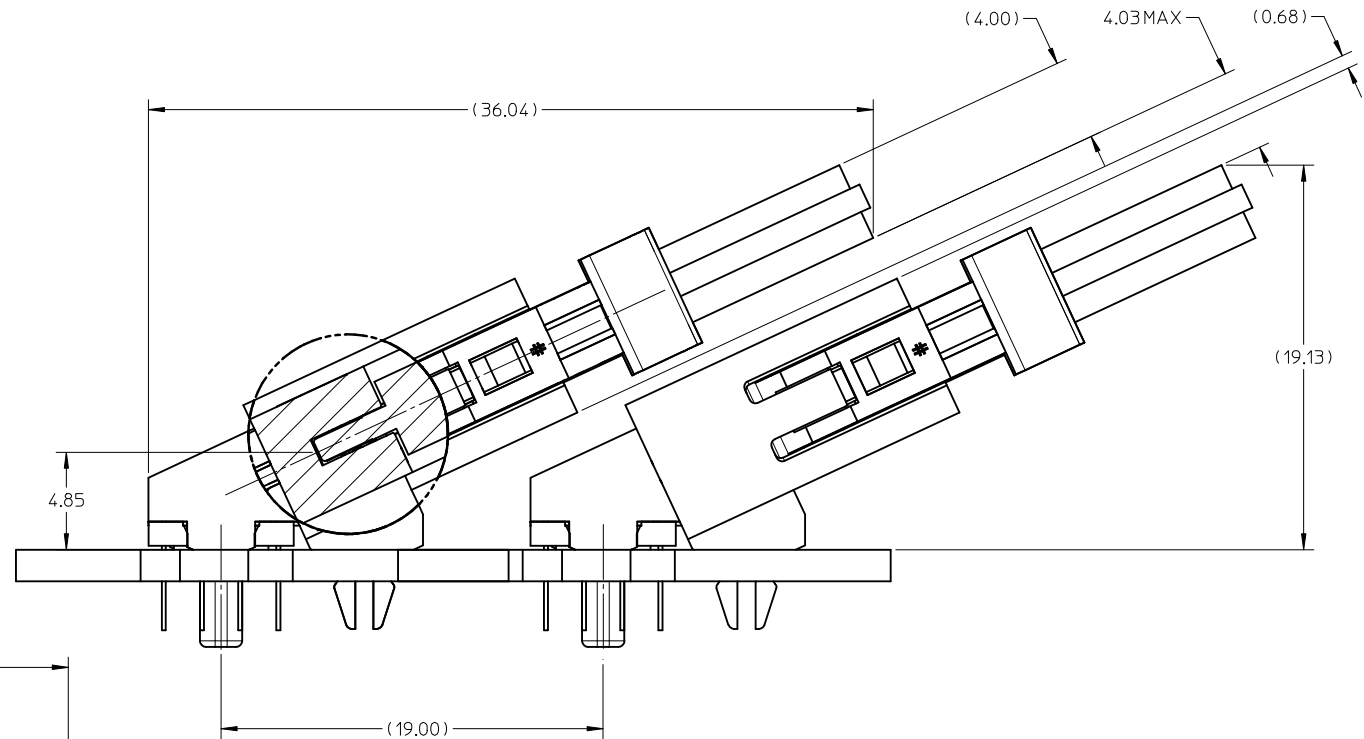
NOTES:

- MATERIALS:
HOUSING & BASEPLATE - LCP, GLASS-FILLED, UL94V-0, BLACK
LATCH - HIGH TEMPERATURE NYLON, GLASS-FILLED, UL94V-0, BLACK
TERMINALS & FORKLICK - COPPER ALLOY
 - PLATING : CONTACT AREA - SEE TABLE IN SHEET 5
SOLDERTAIL - SEE TABLE IN SHEET 5
 - CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS (MEASURE OVER PC PAD)
 - REFER TO PRODUCT SPECIFICATION PS-78373-001 FOR PERFORMANCE SPECIFICATION
 - RECOMMENDED MODULE CARD LAYOUT SHELL BE AS PER JEDEC MO-269
 - PRODUCT SHALL BE PACKED IN TRAY
- MOLEX LOGO , DATE CODE PART NUMBER INDICATED ON HOUSING

ADDED CORING EC NO: S2010-0787 DRW:CCTEH 2010/03/22 CHKD:CGTAN 2011/01/24 APPR:SHLENI 2011/01/24	QUALITY SYMBOLS $F_A=0$ $F_B=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CCTEH	DATE 2008/01/30	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, 25 DEG, T/H			
			4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY CGTAN	DATE 2008/04/07				
			2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	APPROVED BY SHLENI	DATE 2008/04/08	MOLEX INCORPORATED			
		ANGULAR ± 3 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78373-001		SHEET NO. 1 OF 5		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

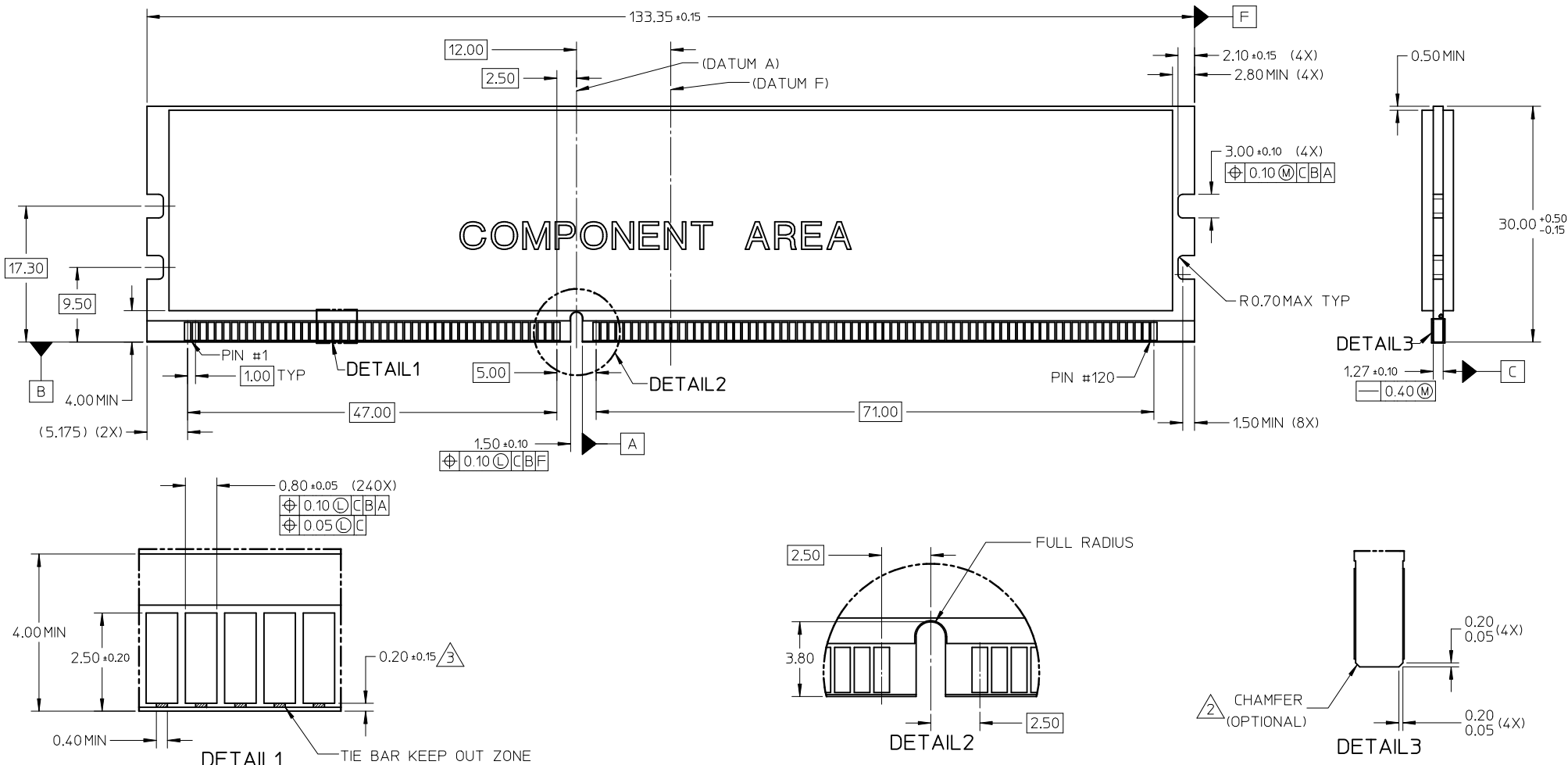


MINIMUM RECOMMENDED ROW TO ROW SPACING WHEN USING 4.00MM THICK MODULE (TYPICAL TSOP PACKAGING)

ADDED CORING EC NO: S2010-0787 DRWN:CTEH 2010/03/22 CHKD:CGTAN 2011/01/24 APPR:SHLENI 2011/01/24	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 3 °	DIMENSION STYLE MM ONLY DRAWN BY DATE CTEH 2008/01/30 CHECKED BY DATE CGTAN 2008/04/07 APPROVED BY DATE SHLENI 2008/04/08 MATERIAL NO.	SCALE NTS DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, 25 DEG, T/H	MOLEX INCORPORATED DOCUMENT NO.	SHEET NO. 2 OF 5	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	SD-78373-001		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	SIZE A3							
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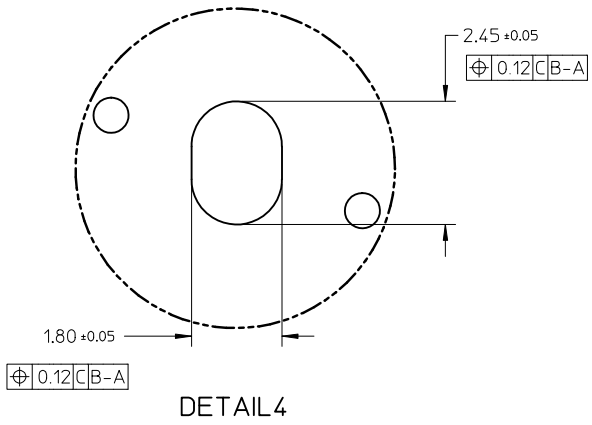
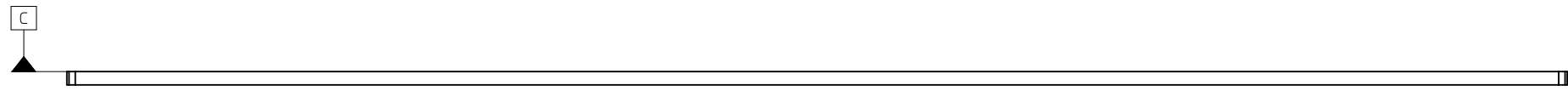
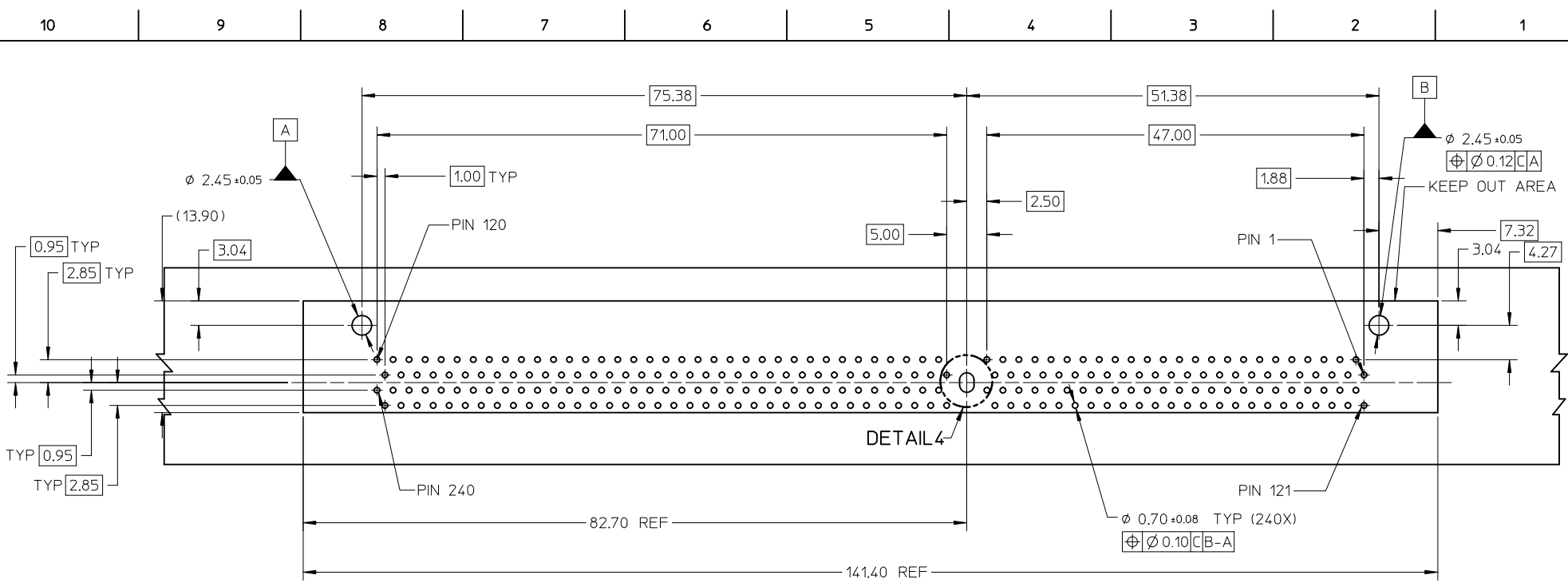
9 8 7 6 5 4 3 2 1

MODULE CARD
DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
(JEDEC MO-269, ISSUE A, 12/05)



- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 μM GOLD PLATING MIN
 OVER 2.00 μM NICKEL
 ALTERNATIVE: 0.05-0.75 μM GOLD PLATING
 OVER 2.00 μM NICKEL MUST
 USE AN ELECTRONIC CONTACT GRADE
 CORROSIVE BARRIER LUBRICANT
 - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
 - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEP OUT ZONE
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

ADDED CORING EC NO: S2010-0787 DRW: CCTEH 2010/03/22 CHKD: CGTAN 2011/01/24 APPR: SHLENI 2011/01/24	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_B=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
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		3 PLACES ± --- ± ---	± 0.25 ± ---	CHECKED BY CGTAN	DATE 2008/04/07	MOLEX INCORPORATED				
		2 PLACES ± --- ± --- 1 PLACE ± --- ± ---	ANGULAR ± 3°	APPROVED BY SHLENI	DATE 2008/04/08	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78373-001	SHEET NO. 3 OF 5		
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PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	PLATING OPTION
78373-0001	CENTER (1.5V)	2.79	3.18	1.57	0.76µM / 30 Mmch MIN GOLD ON CONTACT 2.54µM / 100 Mmch MIN PURE TIN ON SOLDER TAILS 1.27µM / 50 Mmch MIN NICKEL UNDERPLATE
78373-0011		3.18	4.83	2.36	
78373-0111		4.00	4.83	2.59	

ADDED CORING EC NO: S2010-0787 DRW: CCTEH 2010/03/22 CHK: CGTAN 2011/01/24 APPR: SHLENI 2011/01/24	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION																																
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